

AMENDMENTSIn the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (currently amended) A socket or adapter-device adapted for carrying a semiconductor device to be tested, the test socket or adapter device comprising at least one connection pin, wherein the connection pin extends from a lower surface of the socket or adapter device in a downward direction, the connection pin being configured to be connected to a corresponding contact device by solderless surface mounting, and the end section of the connection pin has a shape bent back in an upward direction, the bent back end section of the connection pin electrically contacts an electrical contact of the contact device.

2. (original) The socket or adapter device according to claim 1, wherein the socket or adapter device is a semiconductor device testing adapter, respectively, which is configured for testing a semiconductor device such that it can be loaded with a corresponding semiconductor device.

3. (original) The socket or adapter device according to claim 2, wherein the socket or adapter device is a burn-in testing socket or a burn-in testing adapter, respectively, which is configured for performing a burn-in test and can be loaded with a corresponding semiconductor device.

4. (original) The socket or adapter device according to claim 1, wherein the connection pin is made of a flexible or resilient material.

5. (original) The socket or adapter device according to claim 4, wherein the metal alloy includes copper and/or beryllium.